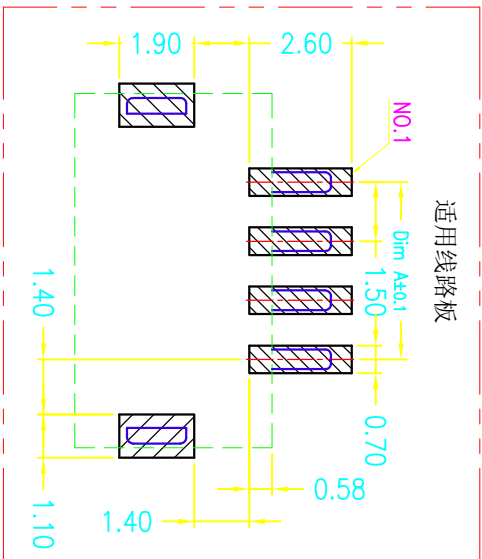
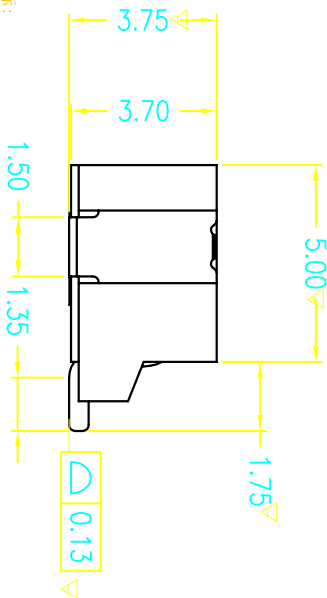
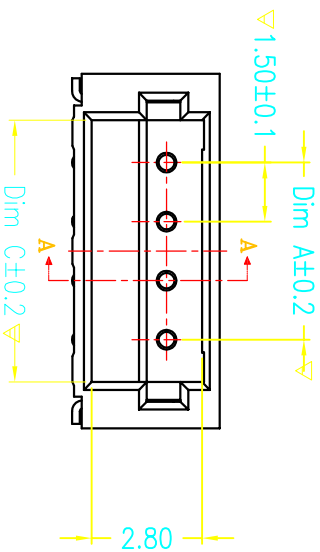
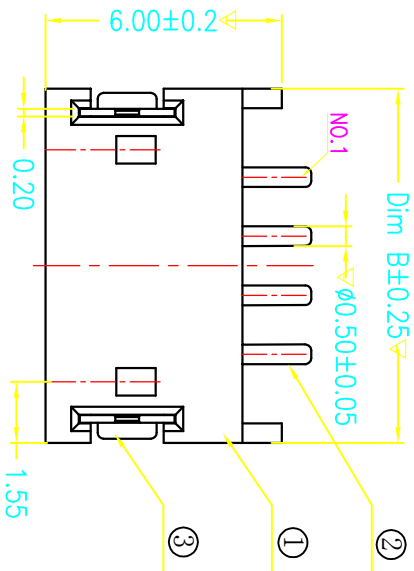
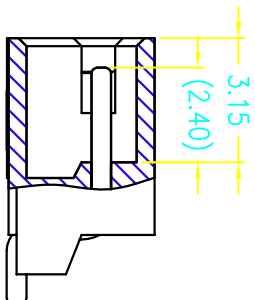
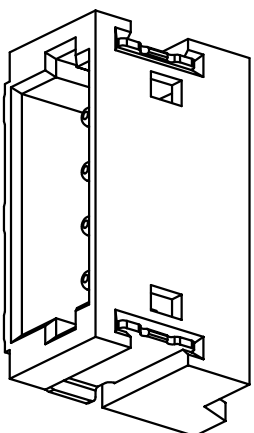


REV(版本号)	DESCRIPTION(描述)	NAME(名字)	DATE(日期)



CKT	Dim A	Dim B	Dim C
2	1.50	6.00	3.65
3	3.00	7.50	5.15
4	4.50	9.00	6.65
5	6.00	10.50	8.15
6	7.50	12.50	9.65
7	9.00	13.50	11.15
8	10.50	15.50	12.65
9	12.50	16.50	14.15
10	13.50	18.50	15.65
11	15.50	19.50	17.15
12	16.50	21.50	18.65
13	18.50	22.50	20.15
14	19.50	24.50	21.65
15	21.50	25.50	23.15
16	22.50	27.50	24.65
17	24.50	28.50	26.15
18	25.50	30.00	27.65
19	27.50	31.50	29.15
20	28.50	33.00	30.65

技术指标:

1. 塑件表面应光洁、无毛边、无明显收缩、缺陷、裂纹等现象。
2. 温度范围: -40° C~85° C.
3. Working temp: -40° C~85° C.
4. 额定电压: 100V, AC/DC.
5. Voltage rating: 100V AC/DC (rms)
6. 接触电阻: ≤40mΩ.
7. Insulation resistance: ≥500MΩ.
8. 绝缘电阻: ≥500MΩ.
9. Insulation resistance: 500MΩ min
10. 额定电流: 2A, AC/DC.
11. Current rating: 2A AC/DC
12. 耐电压: AC 500V/1分钟
13. Withstanding Voltage: 500V AC/minute
14. 8. PIN保持力: 10N min
15. pin retention Force: 10N min
16. 9. 主体材料: ICP UL94-V0, 本色
17. Housing material: ICP UL94-V0, 本色
18. 10. 端子材料: 黄铜C2680, 镀镍50μ" min, 镀亮锡100μ" min
19. Terminal material: Brass C2680, plating Ni 50μ" min, plating Tin 100μ" min
20. 11. 垫片材料: 黄铜C2680, 镀镍50μ" min, 镀亮锡100μ" min
21. Solder tab material: Brass C2680, plating Ni 50μ" min, plating Tin 100μ" min
22. 12. 标有"▽"为重点管控 MAJOR DIMENSION: ▽

深圳市连欣科技有限公司

品名 (TITLE) ZH 卧式 SMF
Pitch: 1.50mm

料号 (PART NO) XDWF-0151WT-**P

比例 (SCALE) 1:1

单位 (UNITS) mm

1 OF 1

尺寸 (SIZE) A4

版本 (REV) A

审核 (APP) Alex

制图 (DR) X1M0

校对 (CHK) Alex

一般公差 (TOLERANCE) X ±0.50 XX ±1.0 X ±0.20 XXX ±0.05 ANGLES ±1°